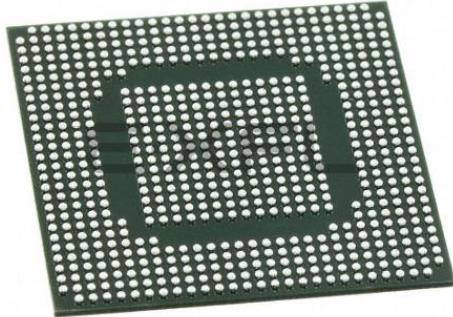


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[**Embedded - System On Chip \(SoC\)**](#): The Heart of Modern Embedded Systems



Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are [**Embedded - System On Chip \(SoC\)**](#)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details

Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	800MHz
Primary Attributes	FPGA - 110K Logic Elements
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	672-FBGA
Supplier Device Package	672-UBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cseba6u23i7n



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Density	Ordering Part Number (OPN)	Static Power Reduction
110K LE	5CSEBA6U19I7LN	
	5CSEBA6U23I7LN	
	5CSXFC6C6U23I7LN	

To estimate total power consumption for a low-power device, listed in [Table 1](#) on page 3:

1. Multiply the Total Static Power reported by the Early Power Estimator (EPE) by the appropriate scale factor:
 - For 25K LE and 40K LE devices, use 0.7
 - For 85K LE and 110K LE devices, use 0.8
2. Add the result from Step 1 on page 4 to the Total Dynamic Power reported by the EPE.

Related Information

[Cyclone V Device Overview](#)

Provides more information about the densities and packages of devices in the Cyclone V family.

Electrical Characteristics

The following sections describe the operating conditions and power consumption of Cyclone V devices.

Operating Conditions

Cyclone V devices are rated according to a set of defined parameters. To maintain the highest possible performance and reliability of the Cyclone V devices, you must consider the operating requirements described in this section.

Absolute Maximum Ratings

This section defines the maximum operating conditions for Cyclone V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms.

The functional operation of the device is not implied for these conditions.

Caution: Conditions outside the range listed in the following table may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.



I/O Standard	V _{CCIO} (V)			V _{REF} (V)			V _{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	V _{CCIO} /2	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	V _{CCIO} /2	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 × V _{CCIO}	0.5 × V _{CCIO}	0.53 × V _{CCIO}	—	V _{CCIO} /2	—
HSUL-12	1.14	1.2	1.3	0.49 × V _{CCIO}	0.5 × V _{CCIO}	0.51 × V _{CCIO}	—	—	—

Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications

Table 17. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Cyclone V Devices

I/O Standard	V _{IL(DC)} (V)		V _{IH(DC)} (V)		V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I _{OL} ⁽¹⁹⁾ (mA)	I _{OH} ⁽¹⁹⁾ (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	V _{REF} - 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} - 0.31	V _{REF} + 0.31	V _{TT} - 0.608	V _{TT} + 0.608	8.1	-8.1
SSTL-2 Class II	-0.3	V _{REF} - 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} - 0.31	V _{REF} + 0.31	V _{TT} - 0.81	V _{TT} + 0.81	16.2	-16.2
SSTL-18 Class I	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	V _{TT} - 0.603	V _{TT} + 0.603	6.7	-6.7
SSTL-18 Class II	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	0.28	V _{CCIO} - 0.28	13.4	-13.4

continued...

(19) To meet the I_{OL} and I_{OH} specifications, you must set the current strength settings accordingly. For example, to meet the SSTL15CI specification (8 mA), you should set the current strength settings to 8 mA. Setting at lower current strength may not meet the I_{OL} and I_{OH} specifications in the datasheet.



Symbol/Description	Condition	Transceiver Speed Grade 5 ⁽³⁰⁾			Transceiver Speed Grade 6			Transceiver Speed Grade 7			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Minimum differential eye opening at the receiver serial input pins ⁽⁴⁰⁾	—	110	—	—	110	—	—	110	—	—	mV
Differential on-chip termination resistors	85- Ω setting	—	85	—	—	85	—	—	85	—	Ω
	100- Ω setting	—	100	—	—	100	—	—	100	—	Ω
	120- Ω setting	—	120	—	—	120	—	—	120	—	Ω
	150- Ω setting	—	150	—	—	150	—	—	150	—	Ω
V _{ICM} (AC coupled)	2.5 V PCML, LVPECL, and LVDS	V _{CCE_GXBL} supply ⁽³⁴⁾⁽³⁵⁾			V _{CCE_GXBL} supply			V _{CCE_GXBL} supply			V
	1.5 V PCML	0.65/0.75/0.8 ⁽⁴¹⁾									V
t _{LTR} ⁽⁴²⁾	—	—	—	10	—	—	10	—	—	10	μ s
t _{LTD} ⁽⁴³⁾	—	—	—	4	—	—	4	—	—	4	μ s
t _{LTD_manual} ⁽⁴⁴⁾	—	—	—	4	—	—	4	—	—	4	μ s
t _{LTR_LTD_manual} ⁽⁴⁵⁾	—	15	—	—	15	—	—	15	—	—	μ s

continued...

- (40) The differential eye opening specification at the receiver input pins assumes that you have disabled the Receiver Equalization feature. If you enable the Receiver Equalization feature, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (41) The AC coupled V_{ICM} = 650 mV for Cyclone V GX and SX in PCIe mode only. The AC coupled V_{ICM} = 750mV for Cyclone V GT and ST in PCIe mode only.
- (42) t_{LTR} is the time required for the receive clock data recovery (CDR) to lock to the input reference clock frequency after coming out of reset.
- (43) t_{LTD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.
- (44) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.



Intel Quartus Prime 1st Post Tap Pre-Emphasis Setting	Intel Quartus Prime V_{OD} Setting							Unit
	10 (200 mV)	20 (400 mV)	30 (600 mV)	35 (700 mV)	40 (800 mV)	45 (900 mV)	50 (1000 mV)	
11	—	10.2	6.09	5.01	4.23	3.61	—	dB
12	—	11.56	6.74	5.51	4.68	3.97	—	dB
13	—	12.9	7.44	6.1	5.12	4.36	—	dB
14	—	14.44	8.12	6.64	5.57	4.76	—	dB
15	—	—	8.87	7.21	6.06	5.14	—	dB
16	—	—	9.56	7.73	6.49	—	—	dB
17	—	—	10.43	8.39	7.02	—	—	dB
18	—	—	11.23	9.03	7.52	—	—	dB
19	—	—	12.18	9.7	8.02	—	—	dB
20	—	—	13.17	10.34	8.59	—	—	dB
21	—	—	14.2	11.1	—	—	—	dB
22	—	—	15.38	11.87	—	—	—	dB
23	—	—	—	12.67	—	—	—	dB
24	—	—	—	13.48	—	—	—	dB
25	—	—	—	14.37	—	—	—	dB
26	—	—	—	—	—	—	—	dB
27	—	—	—	—	—	—	—	dB
28	—	—	—	—	—	—	—	dB
29	—	—	—	—	—	—	—	dB
30	—	—	—	—	—	—	—	dB
31	—	—	—	—	—	—	—	dB

Related Information

SPICE Models for Intel Devices

Provides the Cyclone V HSSI HSPICE models.

Transceiver Compliance Specification

The following table lists the physical medium attachment (PMA) specification compliance of all supported protocol for Cyclone V GX, GT, SX, and ST devices. For more information about the protocol parameter details and compliance specifications, contact your Intel Sales Representative.

Table 29. Transceiver Compliance Specification for All Supported Protocol for Cyclone V GX, GT, SX, and ST Devices

Protocol	Sub-protocol	Data Rate (Mbps)
PCIe	PCIe Gen1	2,500
	PCIe Gen2 ⁽⁵⁰⁾	5,000
	PCIe Cable	2,500
XAUI	XAUI 2135	3,125
Serial RapidIO® (SRIO)	SRIO 1250 SR	1,250
	SRIO 1250 LR	1,250
	SRIO 2500 SR	2,500
	SRIO 2500 LR	2,500
	SRIO 3125 SR	3,125
	SRIO 3125 LR	3,125
	SRIO 5000 SR	5,000
	SRIO 5000 MR	5,000
	SRIO 5000 LR	5,000
Common Public Radio Interface (CPRI)	CPRI E6LV	614.4
	CPRI E6HV	614.4
	CPRI E6LVII	614.4

continued...

(50) For PCIe Gen2 sub-protocol, Intel recommends increasing the V_{CCE_GXBL} and V_{CCL_GXBL} typical value from 1.1 V to 1.2 V for Cyclone V GT and ST FPGA systems which ensure full compliance to the PCIe Gen2 transmit jitter specification. For more information about the maximum full duplex channels recommended in Cyclone V GT and ST devices under this condition, refer to the *Transceiver Protocol Configurations in Cyclone V Devices* chapter.

- [6.144-Gbps Support Capability in Cyclone V GT Devices](#)

Provides more information about the maximum full duplex channels recommended in Cyclone V GT and ST devices for CPRI 6.144 Gbps.

Core Performance Specifications

Clock Tree Specifications

Table 30. Clock Tree Specifications for Cyclone V Devices

Parameter	Performance			Unit
	-C6	-C7, -I7	-C8, -A7	
Global clock and Regional clock	550	550	460	MHz
Peripheral clock	155	155	155	MHz

PLL Specifications

Table 31. PLL Specifications for Cyclone V Devices

This table lists the Cyclone V PLL block specifications. Cyclone V PLL block does not include HPS PLL.

Symbol	Parameter	Condition	Min	Typ	Max	Unit
f_{IN}	Input clock frequency	-C6 speed grade	5	—	670 ⁽⁵²⁾	MHz
		-C7, -I7 speed grades	5	—	622 ⁽⁵²⁾	MHz
		-C8, -A7 speed grades	5	—	500 ⁽⁵²⁾	MHz
f_{INPFD}	Integer input clock frequency to the phase frequency detector (PFD)	—	5	—	325	MHz
f_{FINPFD}	Fractional input clock frequency to the PFD	—	50	—	160	MHz
$f_{VCO}^{(53)}$	PLL voltage-controlled oscillator (VCO) operating range	-C6, -C7, -I7 speed grades	600	—	1600	MHz

continued...

⁽⁵²⁾ This specification is limited in the Intel Quartus Prime software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.



Memory	Mode	Resources Used		Performance			Unit
		ALUTs	Memory	-C6	-C7, -I7	-C8, -A7	
	ROM, all supported width	0	1	420	350	300	MHz
M10K Block	Single-port, all supported widths	0	1	315	275	240	MHz
	Simple dual-port, all supported widths	0	1	315	275	240	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	275	240	180	MHz
	True dual port, all supported widths	0	1	315	275	240	MHz
	ROM, all supported widths	0	1	315	275	240	MHz

Periphery Performance

This section describes the periphery performance, high-speed I/O, and external memory interface.

Actual achievable frequency depends on design and system specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.



Symbol	Condition	-C6			-C7, -I7			-C8, -A7			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$t_{x\ Jitter}$ -True Differential I/O Standards ⁽⁶⁷⁾	SERDES factor J = 1 to 2, uses DDR registers	(65)	—	(66)	(65)	—	(66)	(65)	—	(66)	Mbps
	Emulated Differential I/O Standards with Three External Output Resistor Networks- f_{HSDR} (data rate) ⁽⁶⁷⁾	SERDES factor J = 4 to 10	(65)	—	640	(65)	—	640	(65)	—	550 Mbps
	Emulated Differential I/O Standards with One External Output Resistor Network - f_{HSDR} (data rate)	SERDES factor J = 4 to 10	(65)	—	170	(65)	—	170	(65)	—	170 Mbps
	Total Jitterfor Data Rate, 600 Mbps – 840 Mbps	—	—	350	—	—	380	—	—	500	ps
		—	—	0.21	—	—	0.23	—	—	0.30	UI
	$t_{x\ Jitter}$ -Emulated Differential I/O Standards with Three External Output Resistor Networks	Total Jitter for Data Rate < 640Mbps	—	—	500	—	—	500	—	500	ps
	$t_{x\ Jitter}$ -Emulated Differential I/O Standards with One External Output Resistor Network	Total Jitter for Data Rate < 640Mbps	—	—	0.15	—	—	0.15	—	0.15	UI
t_{DUTY}	TX output clock duty cycle for both True and	45	50	55	45	50	55	45	50	55	%

continued...

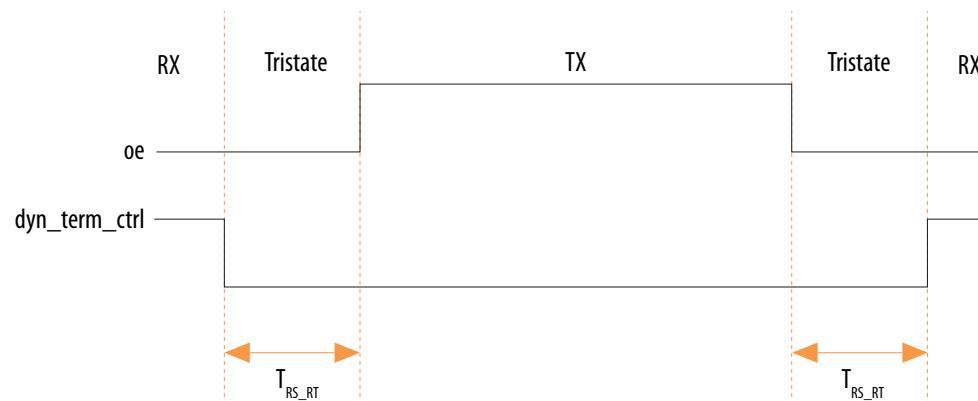
-
- (66) The maximum ideal data rate is the SERDES factor (J) \times PLL max output frequency (f_{out}), provided you can close the design timing and the signal integrity simulation is clean. You can estimate the achievable maximum data rate by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.
 - (67) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine the leftover timing margin.

OCT Calibration Block Specifications

Table 38. OCT Calibration Block Specifications for Cyclone V Devices

Symbol	Description	Min	Typ	Max	Unit
OCTUSRCLK	Clock required by OCT calibration blocks	—	—	20	MHz
T_{OCTCAL}	Number of OCTUSRCLK clock cycles required for R_S OCT/ R_T OCT calibration	—	1000	—	Cycles
$T_{OCTSHIFT}$	Number of OCTUSRCLK clock cycles required for OCT code to shift out	—	32	—	Cycles
T_{RS_RT}	Time required between the <code>dyn_term_ctrl</code> and <code>oe</code> signal transitions in a bidirectional I/O buffer to dynamically switch between R_S OCT and R_T OCT	—	2.5	—	ns

Figure 5. Timing Diagram for oe and dyn_term_ctrl Signals





Duty Cycle Distortion (DCD) Specifications

Table 39. Worst-Case DCD on Cyclone V I/O Pins

The output DCD cycle only applies to the I/O buffer. It does not cover the system DCD.

Symbol	-C6		-C7, -I7		-C8, -A7		Unit
	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	%

HPS Specifications

This section provides HPS specifications and timing for Cyclone V devices.

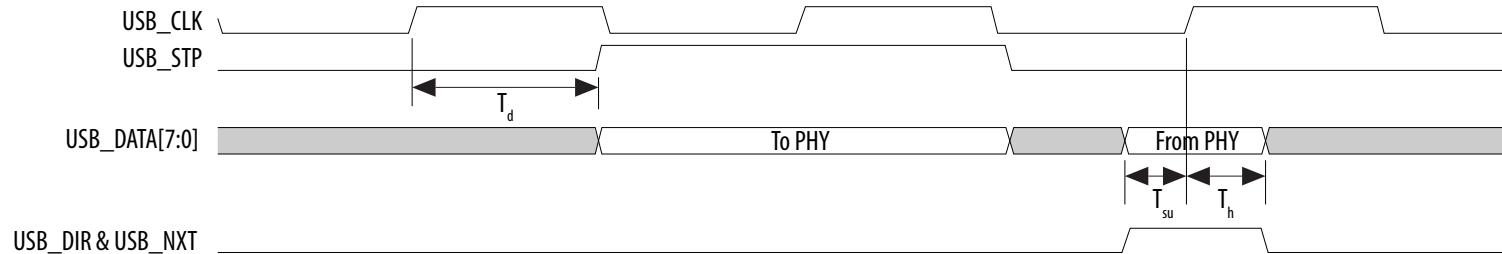
For HPS reset, the minimum reset pulse widths for the HPS cold and warm reset signals (HPS_nRST and HPS_nPOR) are six clock cycles of HPS_CLK1.

HPS Clock Performance

Table 40. HPS Clock Performance for Cyclone V Devices

Symbol/Description	-C6	-C7, -I7	-A7	-C8	Unit
mpu_base_clk (microprocessor unit clock)	925	800	700	600	MHz
main_base_clk (L3/L4 interconnect clock)	400	400	350	300	MHz
h2f_user0_clk	100	100	100	100	MHz
h2f_user1_clk	100	100	100	100	MHz
h2f_user2_clk	200	200	160	160	MHz

Figure 10. USB Timing Diagram



Ethernet Media Access Controller (EMAC) Timing Characteristics

Table 48. Reduced Gigabit Media Independent Interface (RGMII) TX Timing Requirements for Cyclone V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk} (1000Base-T)	TX_CLK clock period	—	8	—	ns
T_{clk} (100Base-T)	TX_CLK clock period	—	40	—	ns
T_{clk} (10Base-T)	TX_CLK clock period	—	400	—	ns
$T_{dutycycle}$	TX_CLK duty cycle	45	—	55	%
T_d	TX_CLK to TXD/TX_CTL output data delay	-0.85	—	0.15	ns

Figure 11. RGMII TX Timing Diagram

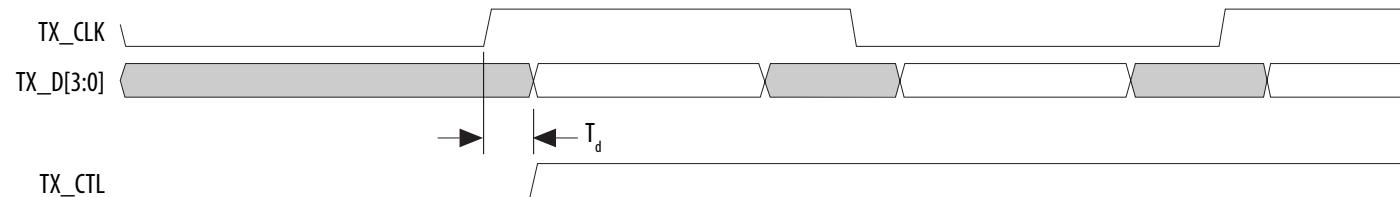


Table 49. RGMII RX Timing Requirements for Cyclone V Devices

Symbol	Description	Min	Typ	Unit
T_{clk} (1000Base-T)	RX_CLK clock period	—	8	ns
T_{clk} (100Base-T)	RX_CLK clock period	—	40	ns
T_{clk} (10Base-T)	RX_CLK clock period	—	400	ns
T_{su}	RX_D/RX_CTL setup time	1	—	ns
T_h	RX_D/RX_CTL hold time	1	—	ns

Figure 12. RGMII RX Timing Diagram

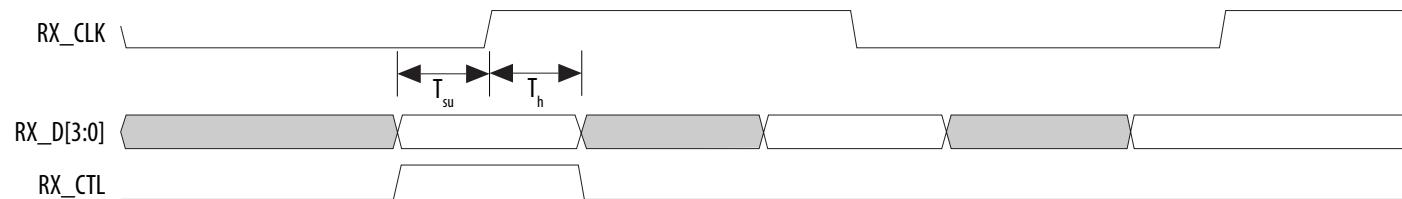
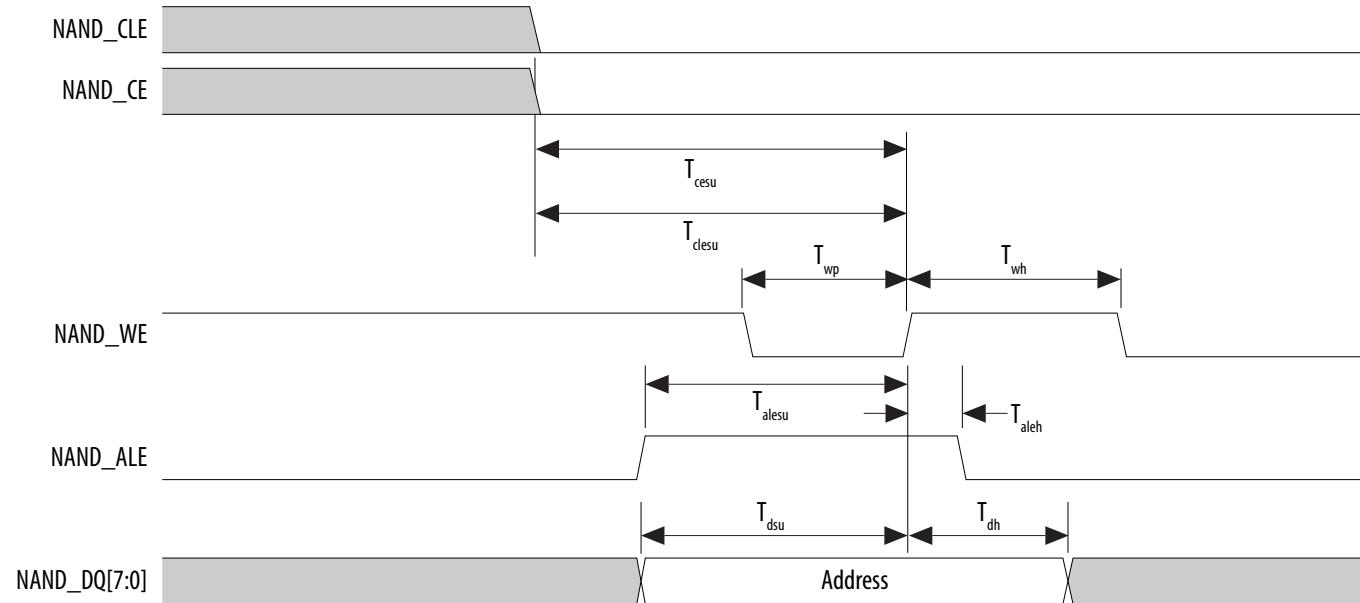


Table 50. Management Data Input/Output (MDIO) Timing Requirements for Cyclone V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk}	MDC clock period	—	400	—	ns
T_d	MDC to MDIO output data delay	10	—	20	ns
T_s	Setup time for MDIO data	10	—	—	ns
T_h	Hold time for MDIO data	0	—	—	ns

Figure 16. NAND Address Latch Timing Diagram





Symbol	Parameter	Minimum	Maximum	Unit
t_{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency	—	125	MHz
t_{CD2UM}	CONF_DONE high to user mode ⁽⁹²⁾	175	437	μs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (T_{init} \times \text{CLKUSR period})$	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Related Information

PS Configuration Timing

Provides the PS configuration timing waveform.

Initialization

Table 63. Initialization Clock Source Option and the Maximum Frequency for Cyclone V Devices

Initialization Clock Source	Configuration Scheme	Maximum Frequency (MHz)	Minimum Number of Clock Cycles
Internal Oscillator	AS, PS, and FPP	12.5	T_{init}
CLKUSR ⁽⁹³⁾	PS and FPP	125	
	AS	100	
DCLK	PS and FPP	125	

(92) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

(93) To enable CLKUSR as the initialization clock source, turn on the **Enable user-supplied start-up clock (CLKUSR)** option in the Intel Quartus Prime software from the **General** panel of the **Device and Pin Options** dialog box.



Variant	Member Code	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits)	Recommended EPCQ Serial Configuration Device ⁽⁹⁴⁾
Cyclone V SX	A4	33,958,560	322,072	EPCQ128
	A5	56,057,632	324,888	EPCQ128
	A6	56,057,632	324,888	EPCQ128
Cyclone V SX	C2	33,958,560	322,072	EPCQ128
	C4	33,958,560	322,072	EPCQ128
	C5	56,057,632	324,888	EPCQ128
	C6	56,057,632	324,888	EPCQ128
Cyclone V ST	D5	56,057,632	324,888	EPCQ128
	D6	56,057,632	324,888	EPCQ128

Minimum Configuration Time Estimation

Table 65. Minimum Configuration Time Estimation for Cyclone V Devices

The estimated values are based on the configuration .rbf sizes in *Uncompressed .rbf Sizes for Cyclone V Devices* table.

Variant	Member Code	Active Serial ⁽⁹⁶⁾			Fast Passive Parallel ⁽⁹⁷⁾		
		Width	DCLK (MHz)	Minimum Configuration Time (ms)	Width	DCLK (MHz)	Minimum Configuration Time (ms)
Cyclone V E	A2	4	100	53	16	125	11
	A4	4	100	53	16	125	11
	A5	4	100	85	16	125	17
	A7	4	100	140	16	125	28

continued...

⁽⁹⁴⁾ The recommended EPCQ serial configuration devices are able to store more than one image.

⁽⁹⁶⁾ DCLK frequency of 100 MHz using external CLKUSR.

⁽⁹⁷⁾ Maximum FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.



Related Information

Configuration Files on page 76

Remote System Upgrades

Table 66. Remote System Upgrade Circuitry Timing Specifications for Cyclone V Devices

Parameter	Minimum	Unit
t _{RU_nCONFIG} ⁽⁹⁸⁾	250	ns
t _{RU_nRSTIMER} ⁽⁹⁹⁾	250	ns

Related Information

- [Remote System Upgrade State Machine](#)
Provides more information about configuration reset (RU_CONFIG) signal.
- [User Watchdog Timer](#)
Provides more information about reset_timer (RU_nRSTIMER) signal.

User Watchdog Internal Oscillator Frequency Specifications

Table 67. User Watchdog Internal Oscillator Frequency Specifications for Cyclone V Devices

Parameter	Minimum	Typical	Maximum	Unit
User watchdog internal oscillator frequency	5.3	7.9	12.5	MHz

I/O Timing

Intel offers two ways to determine I/O timing—the Excel-based I/O timing and the Intel Quartus Prime Timing Analyzer.

⁽⁹⁸⁾ This is equivalent to strobing the reconfiguration input of the Remote Update Intel FPGA IP core high for the minimum timing specification.

⁽⁹⁹⁾ This is equivalent to strobing the reset timer input of the Remote Update Intel FPGA IP core high for the minimum timing specification.

Term	Definition
	<p>The diagram illustrates the timing relationships between four signals: TMS, TDI, TCK, and TDO. TMS and TDI are control signals, while TCK is the clock signal and TDO is the data output. Timing parameters include: - t_{JCP}: Time from TCK rising edge to TMS or TDI transition. - t_{JCH}: Time from TCK falling edge to TMS or TDI transition. - t_{JCL}: Time from TCK rising edge to TMS or TDI transition. - t_{JPSU}: Time from TCK falling edge to TMS or TDI transition. - t_{JPH}: Time from TCK rising edge to TMS or TDI transition. - t_{JPZX}: Time from TCK falling edge to TDO transition. - t_{JPZO}: Time from TCK rising edge to TDO transition. - t_{JPXZ}: Time from TCK falling edge to TDO transition.</p>
PLL specifications	Diagram of PLL specifications
<i>continued...</i>	



Date	Version	Changes
January 2015	2015.01.23	<ul style="list-style-type: none">• Updated the transceiver specification for Cyclone V ST from 5 Gbps to 6.144 Gbps. Updated the note in the following tables:<ul style="list-style-type: none">— Transceiver Power Supply Operating Conditions for Cyclone V GX, GT, SX, and ST Devices— Transceiver Specifications for Cyclone V GX, GT, SX, and ST Devices— Transceiver Compliance Specification for All Supported Protocol for Cyclone V Devices• Updated the description for $V_{CC_AUX_SHARED}$ to "HPS auxiliary power supply". Added a note to state that $V_{CC_AUX_SHARED}$ must be powered by the same source as V_{CC_AUX} for Cyclone V SX C5, C6, D5, and D6 devices, and Cyclone V SE A5 and A6 devices. Updated in the following tables:<ul style="list-style-type: none">— Absolute Maximum Ratings for Cyclone V Devices— HPS Power Supply Operating Conditions for Cyclone V SE, SX, and ST Devices• Added statement in I/O Standard Specifications: You must perform timing closure analysis to determine the maximum achievable frequency for general purpose I/O standards.• Updated the conditions for transceiver reference clock rise time and fall time: Measure at ± 60 mV of differential signal. Added a note to the conditions: REFCLK performance requires to meet transmitter REFCLK phase noise specification.• Updated f_{VCO} maximum value from 1400 MHz to 1600 MHz for -C7 and -I7 speed grades in the PLL specifications table.• Updated the description in Periphery Performance Specifications to mention that proper timing closure is required in design.• Added the following notes in the High-Speed I/O Specifications for Cyclone V Devices table:<ul style="list-style-type: none">— The Cyclone V devices support true RSRS output standard with data rates of up to 230 Mbps using true LVDS output buffer types on all I/O banks.— The Cyclone V devices support true mini-LVDS output standard with data rates of up to 340 Mbps using true LVDS output buffer types on all I/O banks.• Updated HPS Clock Performance main_base_clk specifications from 462 MHz to 400 MHz for -C6 speed grade.• Updated HPS PLL VCO maximum frequency to 1,600 MHz (for -C7, -I7, -A7, and -C8 speed grades) and 1,850 MHz (for -C6 speed grade).• Changed the symbol for HPS PLL input jitter divide value from NR to N.• Removed "Slave select pulse width (Texas Instruments SSP mode)" parameter from the following tables:<ul style="list-style-type: none">— SPI Master Timing Requirements for Cyclone V Devices— SPI Slave Timing Requirements for Cyclone V Devices• Added descriptions to USB Timing Characteristics section in HPS Specifications: PHYs that support LPM mode may not function properly with the USB controller due to a timing issue. It is recommended that designers use the MicroChip USB3300 PHY device that has been proven to be successful on the development board.• Added HPS JTAG timing specifications.• Updated the configuration .rbf size (bits) for Cyclone V devices.• Added a note to Uncompressed .rbf Sizes for Cyclone V Devices table: The recommended EPCQ serial configuration devices are able to store more than one image.

continued...



Date	Version	Changes
February 2012	1.2	<ul style="list-style-type: none">Added automotive speed grade information.Added Figure 2-1.Updated Table 2-3, Table 2-8, Table 2-9, Table 2-19, Table 2-20, Table 2-21, Table 2-22, Table 2-23, Table 2-24, Table 2-25, Table 2-26, Table 2-27, Table 2-28, Table 2-30, Table 2-35, and Table 2-43.Minor text edits.
November 2011	1.1	<ul style="list-style-type: none">Added Table 2-5.Updated Table 2-3, Table 2-4, Table 2-11, Table 2-13, Table 2-20, and Table 2-21.
October 2011	1.0	Initial release.